74AUP2G0604

Low-power inverting buffer with open-drain and inverter

Rev. 1 — 23 November 2012 Product data sheet

1. General description

The 74AUP2G0604 is a single inverting buffer with open-drain output and a single inverter. It features two input pins (nA), an output pin (2Y) and an open-drain output pin (1Y).

Schmitt trigger action at all inputs makes the circuit tolerant of slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using I_{OFF}. The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - JESD8-12 (0.8 V to 1.3 V)
  - JESD8-11 (0.9 V to 1.65 V)
  - JESD8-7 (1.2 V to 1.95 V)
  - JESD8-5 (1.8 V to 2.7 V)
  - JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F Class 3A exceeds 5000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; I_{CC} = 0.9 μA (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options
- Specified from –40 °C to +85 °C and –40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP2G0604GW	–40 °C to +125 °C	SC-88	plastic surface-mounted package; 6 leads	SOT363
74AUP2G0604GM	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP2G0604GF	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74AUP2G0604GN	–40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP2G0604GS	–40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202

4. Marking

Table 2. Marking

Type number	Marking code[1]
74AUP2G0604GW	a6
74AUP2G0604GM	a6
74AUP2G0604GF	a6
74AUP2G0604GN	a6
74AUP2G0604GS	a6

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

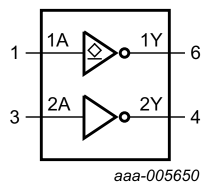

Fig 1. Logic symbol

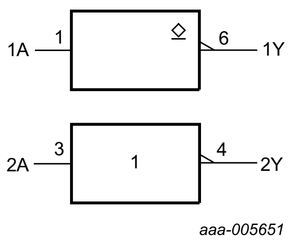

Fig 2. IEC logic symbol

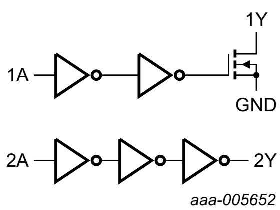

Fig 3. Logic diagram

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6. Pinning information

6.1 Pinning

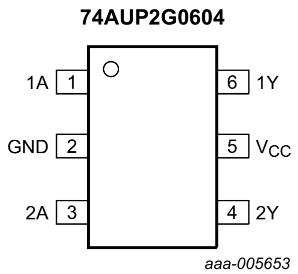

Fig 4. Pin configuration SOT363

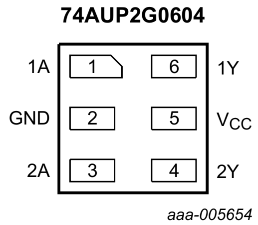

Fig 5. Pin configuration SOT886

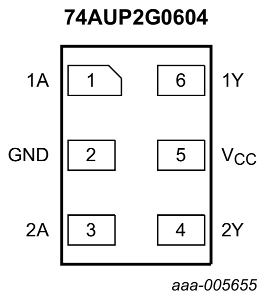

Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1A	1	data input
GND	2	ground (0 V)
2A	3	data input
2Y	4	data output
V_{CC}	5	supply voltage
1Y	6	data output

7. Functional description

Table 4. Function table[1]

Input	Output
1A	**1Y**
L	Z
H	L

[1] H = HIGH voltage level; L = LOW voltage level.

Table 5. Function table[1]

Input	Output
2A	**2Y**
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level.

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8. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V		–50	-	mA
V_I	input voltage		[1]	–0.5	+4.6	V
I_{OK}	output clamping current	$V_O < 0$ V		–50	-	mA
V_O	output voltage	Active mode and Power-down mode	[1]	–0.5	+4.6	V
I_O	output current	$V_O = 0$ V to V_{CC}				
		1Y		-	+20	mA
		2Y		-	±20	mA
I_{CC}	supply current			-	50	mA
I_{GND}	ground current			–50	-	mA
T_{stg}	storage temperature			–65	+150	°C
P_{tot}	total power dissipation	T_{amb} = –40 °C to +125 °C	[2]	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SC-88 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.
For XSON6 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 7. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.8	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	Active mode	0	V_{CC}	V
		Power-down mode; V_{CC} = 0 V	0	3.6	V
T_{amb}	ambient temperature		–40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 0.8 V to 3.6 V	0	200	ns/V

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10. Static characteristics

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 0.8 V	0.70 × V_{CC}	-	-	V
		V_{CC} = 0.9 V to 1.95 V	0.65 × V_{CC}	-	-	V
		V_{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V_{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 0.8 V	-	-	0.30 × V_{CC}	V
		V_{CC} = 0.9 V to 1.95 V	-	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V_{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	2Y; V_I = V_{IH} or V_{IL}				
		I_O = −20 μA; V_{CC} = 0.8 V to 3.6 V	V_{CC} − 0.1	-	-	V
		I_O = −1.1 mA; V_{CC} = 1.1 V	0.75 × V_{CC}	-	-	V
		I_O = −1.7 mA; V_{CC} = 1.4 V	1.11	-	-	V
		I_O = −1.9 mA; V_{CC} = 1.65 V	1.32	-	-	V
		I_O = −2.3 mA; V_{CC} = 2.3 V	2.05	-	-	V
		I_O = −3.1 mA; V_{CC} = 2.3 V	1.9	-	-	V
		I_O = −2.7 mA; V_{CC} = 3.0 V	2.72	-	-	V
		I_O = −4.0 mA; V_{CC} = 3.0 V	2.6	-	-	V
V_{OL}	LOW-level output voltage	1Y, 2Y; V_I = V_{IH} or V_{IL}				
		I_O = 20 μA; V_{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I_O = 1.1 mA; V_{CC} = 1.1 V	-	-	0.3 × V_{CC}	V
		I_O = 1.7 mA; V_{CC} = 1.4 V	-	-	0.31	V
		I_O = 1.9 mA; V_{CC} = 1.65 V	-	-	0.31	V
		I_O = 2.3 mA; V_{CC} = 2.3 V	-	-	0.31	V
		I_O = 3.1 mA; V_{CC} = 2.3 V	-	-	0.44	V
		I_O = 2.7 mA; V_{CC} = 3.0 V	-	-	0.31	V
		I_O = 4.0 mA; V_{CC} = 3.0 V	-	-	0.44	V
I_I	input leakage current	V_I = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.1	μA
I_{OFF}	power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V	-	-	±0.2	μA
ΔI_{OFF}	additional power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V to 0.2 V	-	-	±0.2	μA
I_{CC}	supply current	V_I = GND or V_{CC}; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V	-	-	0.5	μA
ΔI_{CC}	additional supply current	V_I = V_{CC} − 0.6 V; I_O = 0 A; V_{CC} = 3.3 V	-	-	40	μA
C_I	input capacitance	V_{CC} = 0 V to 3.6 V; V_I = GND or V_{CC}	-	0.8	-	pF

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Table 8. Static characteristics *...continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_O	output capacitance	V_O = GND; V_{CC} = 0 V				
		1Y output; enabled	-	1.7	-	pF
		1Y output; disabled	-	1.1	-	pF
		2Y output	-	1.7	-	pF
T_{amb} = −40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 0.8 V	0.70 × V_{CC}	-	-	V
		V_{CC} = 0.9 V to 1.95 V	0.65 × V_{CC}	-	-	V
		V_{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V_{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 0.8 V	-	-	0.30 × V_{CC}	V
		V_{CC} = 0.9 V to 1.95 V	-	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V_{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	2Y; V_I = V_{IH} or V_{IL}				
		I_O = −20 μA; V_{CC} = 0.8 V to 3.6 V	V_{CC} − 0.1	-	-	V
		I_O = −1.1 mA; V_{CC} = 1.1 V	0.7 × V_{CC}	-	-	V
		I_O = −1.7 mA; V_{CC} = 1.4 V	1.03	-	-	V
		I_O = −1.9 mA; V_{CC} = 1.65 V	1.30	-	-	V
		I_O = −2.3 mA; V_{CC} = 2.3 V	1.97	-	-	V
		I_O = −3.1 mA; V_{CC} = 2.3 V	1.85	-	-	V
		I_O = −2.7 mA; V_{CC} = 3.0 V	2.67	-	-	V
		I_O = −4.0 mA; V_{CC} = 3.0 V	2.55	-	-	V
V_{OL}	LOW-level output voltage	1Y, 2Y; V_I = V_{IH} or V_{IL}				
		I_O = 20 μA; V_{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I_O = 1.1 mA; V_{CC} = 1.1 V	-	-	0.3 × V_{CC}	V
		I_O = 1.7 mA; V_{CC} = 1.4 V	-	-	0.37	V
		I_O = 1.9 mA; V_{CC} = 1.65 V	-	-	0.35	V
		I_O = 2.3 mA; V_{CC} = 2.3 V	-	-	0.33	V
		I_O = 3.1 mA; V_{CC} = 2.3 V	-	-	0.45	V
		I_O = 2.7 mA; V_{CC} = 3.0 V	-	-	0.33	V
		I_O = 4.0 mA; V_{CC} = 3.0 V	-	-	0.45	V
I_I	input leakage current	V_I = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.5	μA
I_{OFF}	power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V	-	-	±0.5	μA
ΔI_{OFF}	additional power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V to 0.2 V	-	-	±0.6	μA
I_{CC}	supply current	V_I = GND or V_{CC}; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI_{CC}	additional supply current	V_I = V_{CC} − 0.6 V; I_O = 0 A; V_{CC} = 3.3 V	-	-	50	μA

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Table 8. Static characteristics *...continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = −40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 0.8 V	0.75 × V_{CC}	-	-	V
		V_{CC} = 0.9 V to 1.95 V	0.70 × V_{CC}	-	-	V
		V_{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V_{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 0.8 V	-	-	0.25 × V_{CC}	V
		V_{CC} = 0.9 V to 1.95 V	-	-	0.30 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V_{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	2Y; V_I = V_{IH} or V_{IL}				
		I_O = −20 μA; V_{CC} = 0.8 V to 3.6 V	V_{CC} − 0.11	-	-	V
		I_O = −1.1 mA; V_{CC} = 1.1 V	0.6 × V_{CC}	-	-	V
		I_O = −1.7 mA; V_{CC} = 1.4 V	0.93	-	-	V
		I_O = −1.9 mA; V_{CC} = 1.65 V	1.17	-	-	V
		I_O = −2.3 mA; V_{CC} = 2.3 V	1.77	-	-	V
		I_O = −3.1 mA; V_{CC} = 2.3 V	1.67	-	-	V
		I_O = −2.7 mA; V_{CC} = 3.0 V	2.40	-	-	V
		I_O = −4.0 mA; V_{CC} = 3.0 V	2.30	-	-	V
V_{OL}	LOW-level output voltage	1Y, 2Y; V_I = V_{IH} or V_{IL}				
		I_O = 20 μA; V_{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I_O = 1.1 mA; V_{CC} = 1.1 V	-	-	0.33 × V_{CC}	V
		I_O = 1.7 mA; V_{CC} = 1.4 V	-	-	0.41	V
		I_O = 1.9 mA; V_{CC} = 1.65 V	-	-	0.39	V
		I_O = 2.3 mA; V_{CC} = 2.3 V	-	-	0.36	V
		I_O = 3.1 mA; V_{CC} = 2.3 V	-	-	0.50	V
		I_O = 2.7 mA; V_{CC} = 3.0 V	-	-	0.36	V
		I_O = 4.0 mA; V_{CC} = 3.0 V	-	-	0.50	V
I_I	input leakage current	V_I = GND to 3.6 V; V_{CC} = 0 V to 3.6 V	-	-	±0.75	μA
I_{OFF}	power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V	-	-	±0.75	μA
ΔI_{OFF}	additional power-off leakage current	V_I or V_O = 0 V to 3.6 V; V_{CC} = 0 V to 0.2 V	-	-	±0.75	μA
I_{CC}	supply current	V_I = GND or V_{CC}; I_O = 0 A; V_{CC} = 0.8 V to 3.6 V	-	-	1.4	μA
ΔI_{CC}	additional supply current	V_I = V_{CC} − 0.6 V; I_O = 0 A; V_{CC} = 3.3 V	-	-	75	μA

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11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 8.

Symbol	Parameter	Conditions		25 °C			−40 °C to +125 °C			Unit
				Min	Typ[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C_L = 5 pF										
t_{pd}	propagation delay	1A to 1Y or 2A to 2Y; see Figure 7	[2]							
		V_{CC} = 0.8 V		-	14.4	-	-	-	-	ns
		V_{CC} = 1.1 V to 1.3 V		2.3	4.7	10.3	2.0	11.4	12.6	ns
		V_{CC} = 1.4 V to 1.6 V		1.8	3.4	6.4	1.5	7.4	8.2	ns
		V_{CC} = 1.65 V to 1.95 V		1.5	2.9	5.0	1.2	5.9	6.5	ns
		V_{CC} = 2.3 V to 2.7 V		1.2	2.3	3.9	1.0	4.5	5.0	ns
		V_{CC} = 3.0 V to 3.6 V		1.1	2.2	3.3	0.8	3.9	4.3	ns
C_L = 10 pF										
t_{pd}	propagation delay	1A to 1Y or 2A to 2Y; see Figure 7	[2]							
		V_{CC} = 0.8 V		-	17.7	-	-	-	-	ns
		V_{CC} = 1.1 V to 1.3 V		2.7	5.7	12.2	2.5	13.7	15.1	ns
		V_{CC} = 1.4 V to 1.6 V		2.2	4.1	7.5	2.0	8.7	9.6	ns
		V_{CC} = 1.65 V to 1.95 V		1.9	3.6	5.9	1.7	7.0	7.7	ns
		V_{CC} = 2.3 V to 2.7 V		1.7	2.9	4.6	1.4	5.4	6.0	ns
		V_{CC} = 3.0 V to 3.6 V		1.6	3.0	4.6	1.2	4.9	5.4	ns
C_L = 15 pF										
t_{pd}	propagation delay	1A to 1Y or 2A to 2Y; see Figure 7	[2]							
		V_{CC} = 0.8 V		-	21.1	-	-	-	-	ns
		V_{CC} = 1.1 V to 1.3 V		3.2	6.6	13.0	2.9	15.8	17.4	ns
		V_{CC} = 1.4 V to 1.6 V		2.6	4.7	8.6	2.3	10.0	11.0	ns
		V_{CC} = 1.65 V to 1.95 V		2.3	4.3	6.7	2.1	8.0	8.8	ns
		V_{CC} = 2.3 V to 2.7 V		2.1	3.4	5.1	1.7	6.1	6.8	ns
		V_{CC} = 3.0 V to 3.6 V		2.0	3.6	6.0	1.5	6.5	7.2	ns
C_L = 30 pF										
t_{pd}	propagation delay	1A to 1Y or 2A to 2Y; see Figure 7	[2]							
		V_{CC} = 0.8 V		-	30.7	-	-	-	-	ns
		V_{CC} = 1.1 V to 1.3 V		4.4	9.1	16.5	3.9	19.3	21.3	ns
		V_{CC} = 1.4 V to 1.6 V		3.6	6.6	10.8	3.2	12.9	14.2	ns
		V_{CC} = 1.65 V to 1.95 V		3.2	6.1	10.7	2.9	11.0	12.1	ns
		V_{CC} = 2.3 V to 2.7 V		2.9	4.9	7.2	2.6	7.8	8.6	ns
		V_{CC} = 3.0 V to 3.6 V		2.9	5.4	10.5	2.5	10.8	11.9	ns

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Table 9. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 8.

Symbol	Parameter	Conditions	25 °C			−40 °C to +125 °C			Unit
			Min	Typ[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C_L = 5 pF, 10 pF, 15 pF and 30 pF									
C_{PD}	power dissipation capacitance	1A to 1Y; f_i=1 MHz; V_I = GND to V_{CC} [3][4]							
		V_{CC} = 0.8 V	-	0.5	-	-	-	-	pF
		V_{CC} = 1.1 V to 1.3 V	-	0.6	-	-	-	-	pF
		V_{CC} = 1.4 V to 1.6 V	-	0.7	-	-	-	-	pF
		V_{CC} = 1.65 V to 1.95 V	-	0.7	-	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V	-	1.0	-	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V	-	1.2	-	-	-	-	pF
		2A to 2Y; f_i=1 MHz; V_I = GND to V_{CC} [3][5]							
		V_{CC} = 0.8 V	-	2.5	-	-	-	-	pF
		V_{CC} = 1.1 V to 1.3 V	-	2.7	-	-	-	-	pF
		V_{CC} = 1.4 V to 1.6 V	-	2.8	-	-	-	-	pF
		V_{CC} = 1.65 V to 1.95 V	-	3.0	-	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V	-	3.5	-	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V	-	4.0	-	-	-	-	pF

[1] All typical values are measured at nominal V_{CC}.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}(2A to 2Y) and t_{PLZ} and t_{PZL}(1A to 1Y).

[3] All specified values are the average typical values over all stated loads.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N$ where:
f_i = input frequency in MHz;
C_L = load capacitance in pF;
N = number of inputs switching;

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

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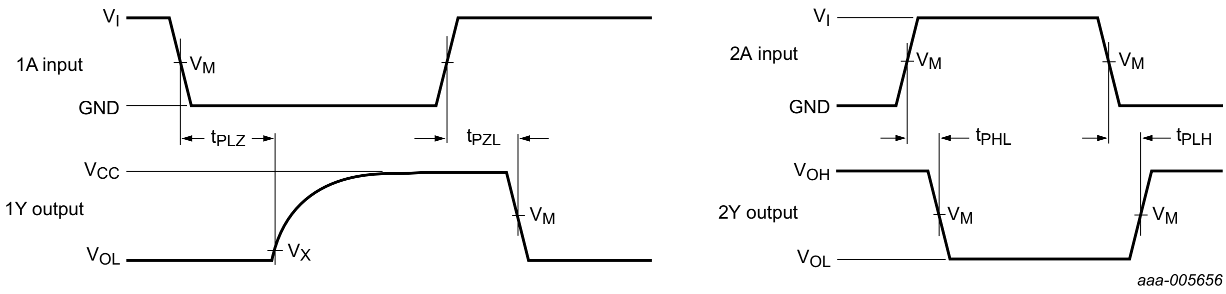
12. Waveforms



Measurement points are given in Table 10.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. The data input 1A to output 1Y and input 2A to output 2Y propagation delays

Table 10. Measurement points

Supply voltage	Output		Input		
V_{CC}	V_M	V_X	V_M	V_I	$t_r = t_f$
0.8 V to 1.6 V	0.5 × V_{CC}	V_{OL} + 0.1 V	0.5 × V_{CC}	V_{CC}	≤ 3.0 ns
1.65 V to 2.7 V	0.5 × V_{CC}	V_{OL} + 0.15 V	0.5 × V_{CC}	V_{CC}	≤ 3.0 ns
3.0 V to 3.6 V	0.5 × V_{CC}	V_{OL} + 0.3 V	0.5 × V_{CC}	V_{CC}	≤ 3.0 ns

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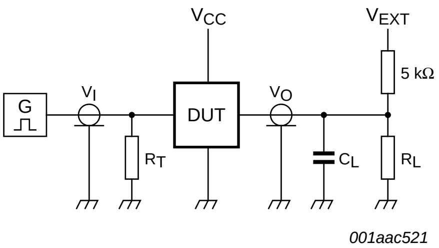

Test data is given in Table 11.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 11. Test data

Supply voltage	Load		V_{EXT}		
V_{CC}	C_L	R_L [1]	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V_{CC}

[1] For measuring enable and disable times, R_L = 5 kΩ. For measuring propagation delays, set-up and hold times, and pulse width, R_L = 1 MΩ.

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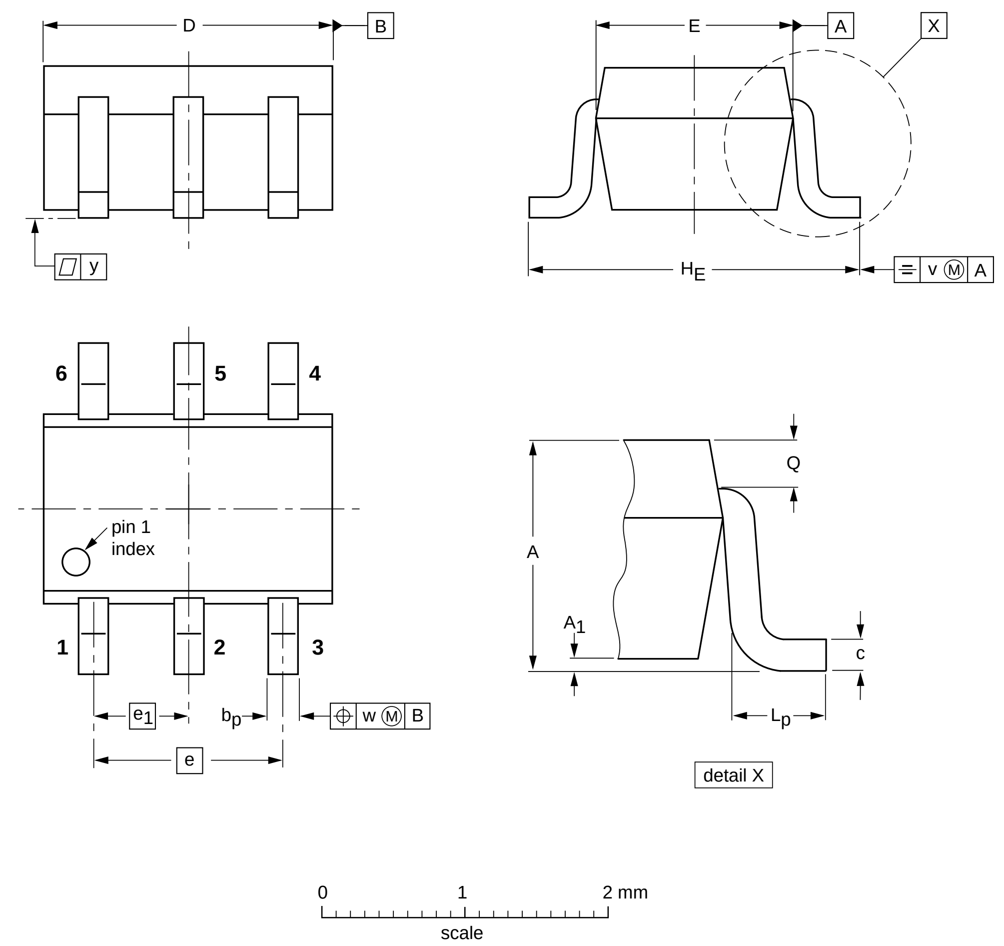
13. Package outline

Plastic surface-mounted package; 6 leads **SOT363**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT363			SC-88			~~04-11-08~~ 06-03-16

Fig 9. Package outline SOT363 (SC-88)

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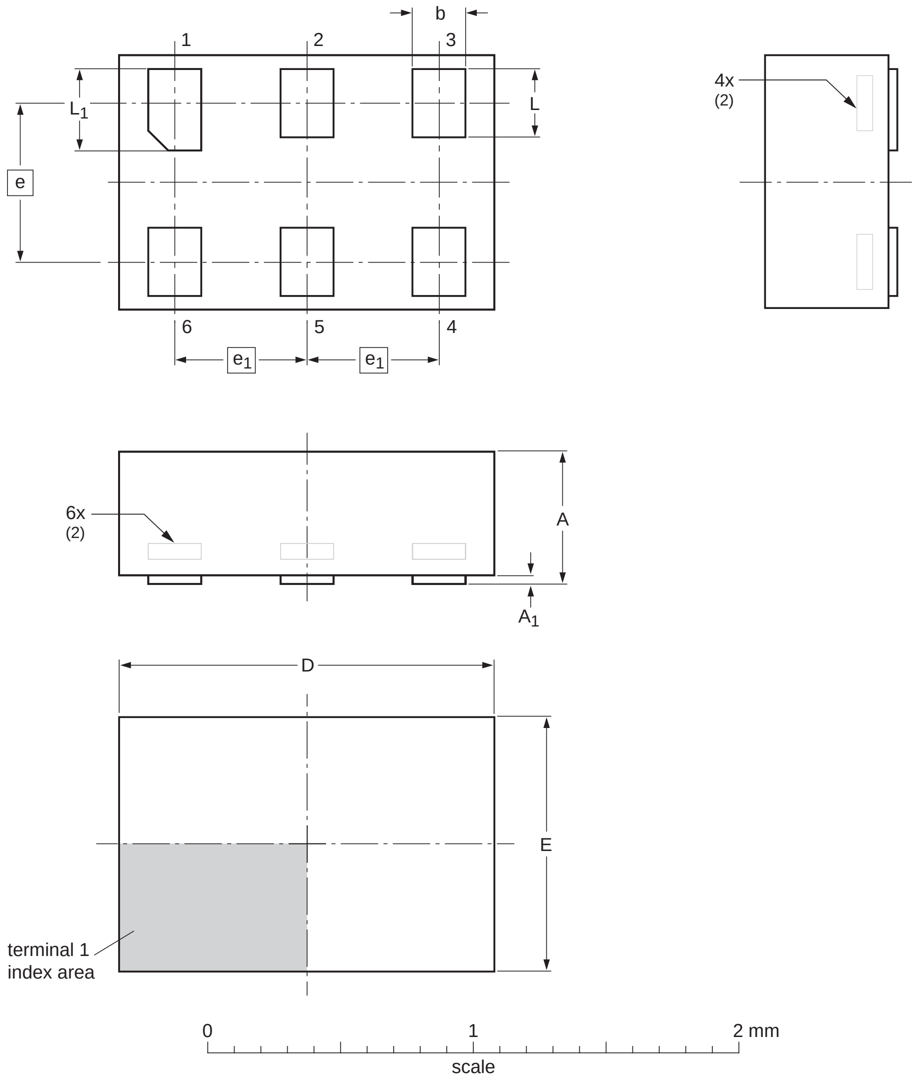
XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm SOT886



Dimensions (mm are the original dimensions)

Unit		$A^{(1)}$	A_1	b	D	E	e	e_1	L	L_1
	max	0.5	0.04	0.25	1.50	1.05			0.35	0.40
mm	nom			0.20	1.45	1.00	0.6	0.5	0.30	0.35
	min			0.17	1.40	0.95			0.27	0.32

Notes
1. Including plating thickness.
2. Can be visible in some manufacturing processes.

sot886_po

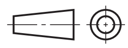
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT886		MO-252				~~04-07-22~~ 12-01-05

Fig 10. Package outline SOT886 (XSON6)

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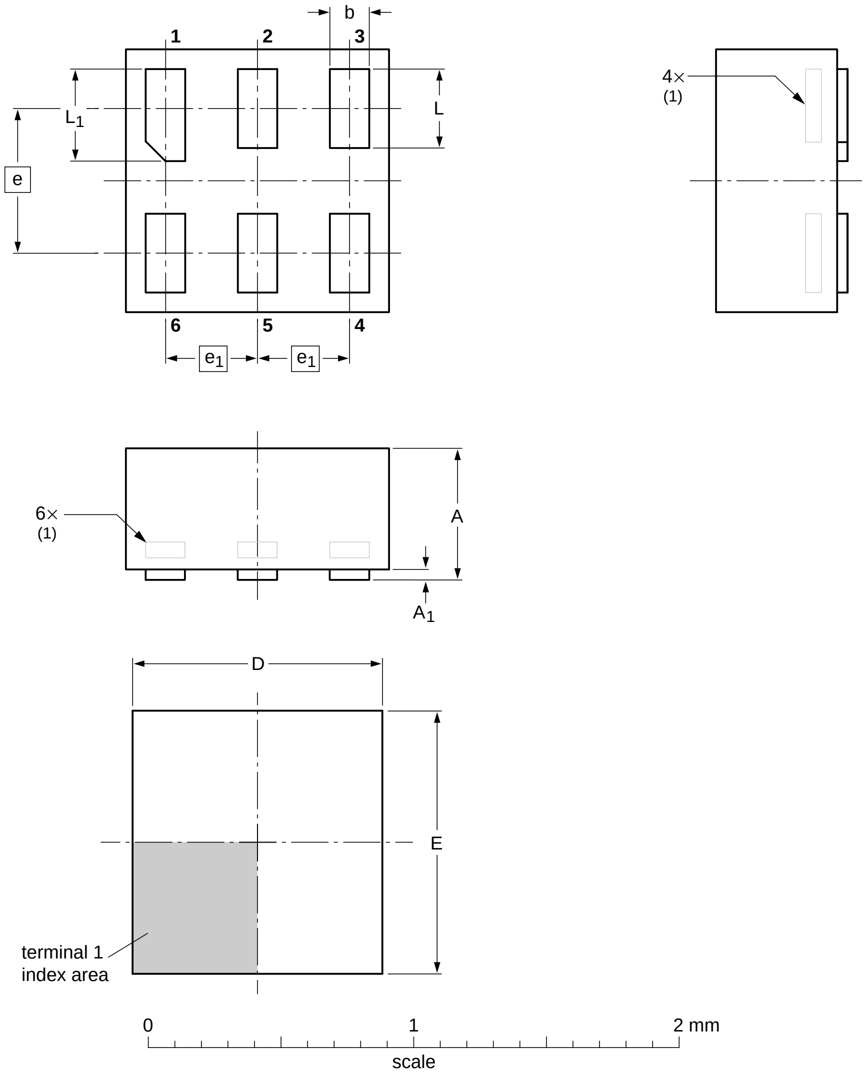
XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm — SOT891



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A_1 max	b	D	E	e	e_1	L	L_1
mm	0.5	0.04	0.20 0.12	1.05 0.95	1.05 0.95	0.55	0.35	0.35 0.27	0.40 0.32

Note

1. Can be visible in some manufacturing processes.

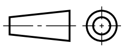
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT891						~~05-04-06~~ 07-05-15

Fig 11. Package outline SOT891 (XSON6)

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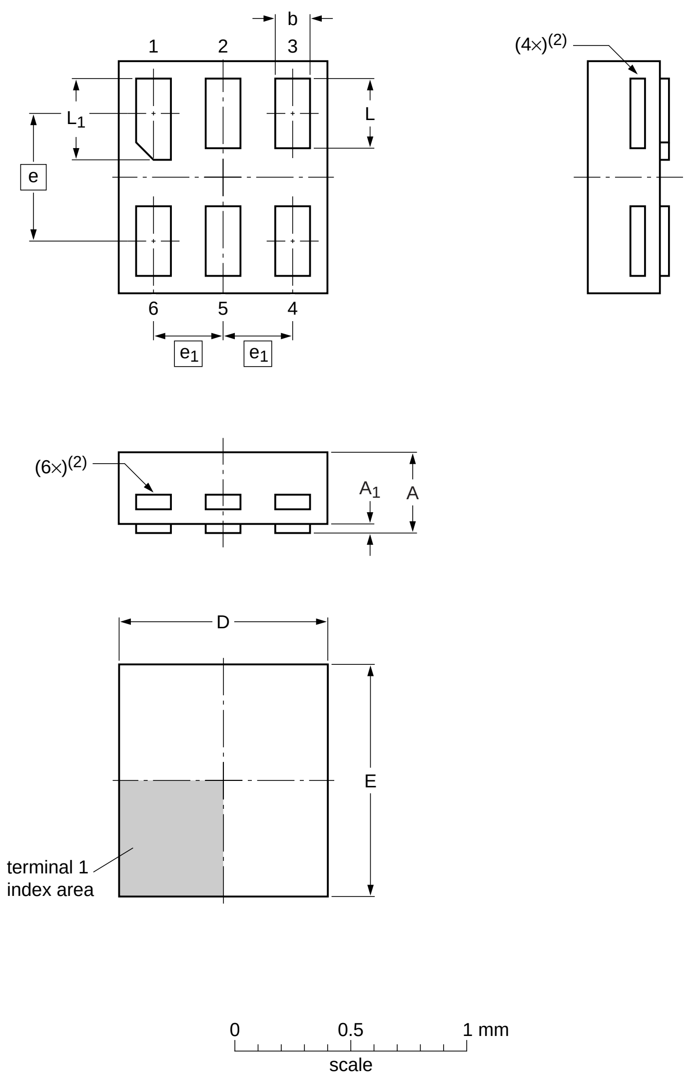
XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm **SOT1115**



Dimensions

Unit		A(1)	A_1	b	D	E	e	e_1	L	L_1
mm	max	0.35	0.04	0.20	0.95	1.05			0.35	0.40
	nom			0.15	0.90	1.00	0.55	0.3	0.30	0.35
	min			0.12	0.85	0.95			0.27	0.32

Note
1. Including plating thickness.
2. Visible depending upon used manufacturing technology.

sot1115_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1115						~~10-04-02~~ 10-04-07

Fig 12. Package outline SOT1115 (XSON6)

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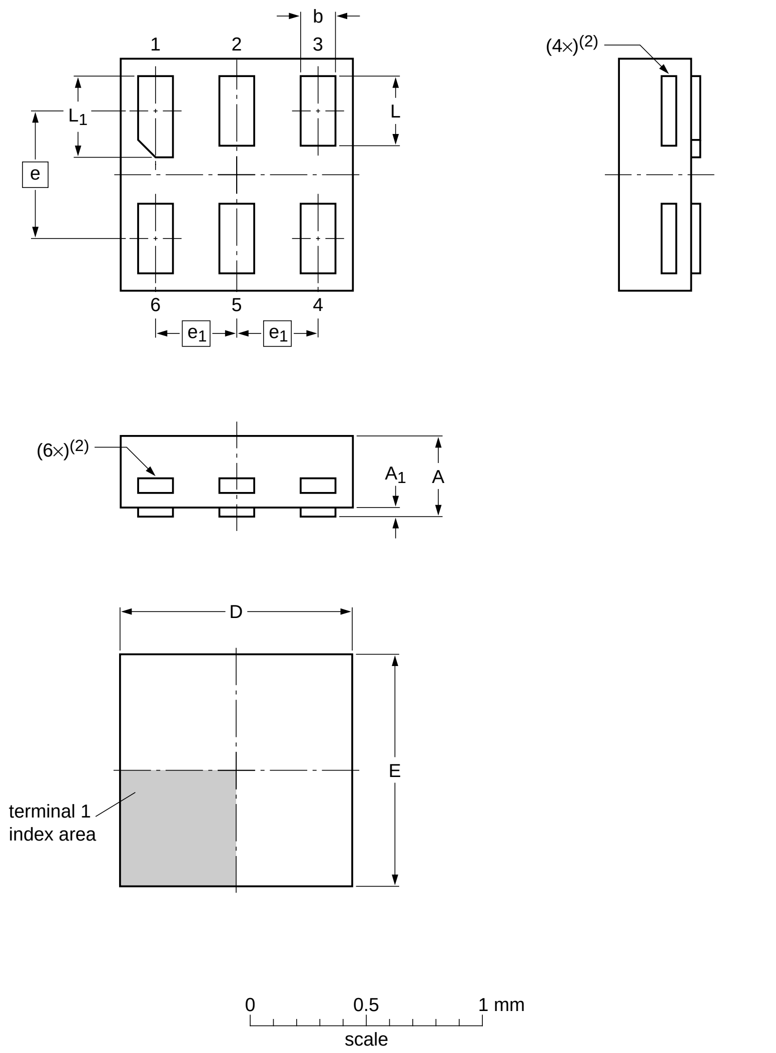
**XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm** **SOT1202**



Dimensions

Unit		A(1)	A_1	b	D	E	e	e_1	L	L_1
	max	0.35	0.04	0.20	1.05	1.05			0.35	0.40
mm	nom			0.15	1.00	1.00	0.55	0.35	0.30	0.35
	min			0.12	0.95	0.95			0.27	0.32

Note
1. Including plating thickness.
2. Visible depending upon used manufacturing technology.

sot1202_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1202						~~10-04-02~~ 10-04-06

Fig 13. Package outline SOT1202 (XSON6)

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14. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

15. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP2G0604 v.1	20121123	Product data sheet	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term ‘short data sheet’ is explained in section “Definitions”.

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